

IN THE ABSTRACT:

Please amend the Abstract originally appearing on page 17 of the application as follows:

ABSTRACT OF THE DISCLOSURE

A dense semiconductor flip-chip device assembly is provided with a heat sink/spreading/dissipating member ~~which~~ that is formed as a paddle of a metallic paddle frame in a strip of paddle frames. ~~Dice~~ Semiconductor dice are bonded to the paddles ~~by e.g.~~ by, e.g., conventional semiconductor die attach ~~attachment~~ methods, enabling bump attachment and testing to be conducted before detachment from the paddle frame strip.